**Office of Student Placements**

**Indian Institute of Technology, Jodhpur**

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**JOB ANNOUCEMENT FORM**

**(2019-20)**

***Please send completed form with attachments to:*** [***placement@iitj.ac.in***](mailto:placement@iitj.ac.in)

|  |  |
| --- | --- |
| Name of the Company |  |
| Nature of Business |  |
| Company Website |  |
| Job Designation |  |
| Tentative Joining Date |  |
| Tentative Job Location |  |
| Job Description |  |

**Please mark the discipline(s) either (Yes or No) in which you are interested to recruit in:**

|  |  |
| --- | --- |
| **Name of the Program** | **Yes/No** |
| **B.Tech.** | |
| Mechanical Engineering |  |
| Electrical Engineering |  |
| Computer Science |  |
| **M.Tech.** | |
| Mechanical Engineering |  |
| Electrical Engineering |  |
| Computer Science and Engineering |  |
| Bioscience and Bio- Engineering |  |
| Metallurgical and Material Engineering |  |

|  |  |
| --- | --- |
| **M.Sc.** | |
| Physics |  |
| Chemistry |  |
| Mathematics |  |
| **Ph.D.** | |
| Mechanical Engineering |  |
| Electrical Engineering |  |
| Computer Science and Engineering |  |
| Physics |  |
| Chemistry |  |
| Mathematics |  |
| Humanities & Social sciences |  |
| Biosciences and Bioengineering |  |
| Metallurgical and Materials Engineering |  |

**Salary Details (\*In lacs per annum)**

|  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- |
| Program | Basic | HRA | Others | Take Home | Cost to Company |
| B.Tech |  |  |  |  |  |
| M.Tech / M.Sc. |  |  |  |  |  |
| Ph.D. |  |  |  |  |  |

**Please provide a detailed breakup of the salary/perks as an attachment to mail or attach it below.**

1. **Is there a service bond/contract (Yes/No)?**

* If yes, what will be the duration, amount and stipulated conditions?

|  |
| --- |
|  |

**2. Physical Fitness: Yes / No**

|  |
| --- |
|  |

**3. Medical Eligibility Criteria (If Any)**

|  |
| --- |
|  |

**4. Allow Backlogs (Yes/No)**

|  |
| --- |
|  |

**5. If selected, Offer Letter will be issued within?**

|  |
| --- |
|  |

**Selection Process**

1. CGPA Eligibility Criteria : **B.Tech M.Tech**

Any other criteria please specify:

|  |
| --- |
|  |

1. Shortlist from Resumes (Yes/No) :

Any other criteria, please specify:

|  |
| --- |
|  |

1. Further rounds for the shortlisted students

|  |  |  |  |
| --- | --- | --- | --- |
| **Selection Rounds** | **Yes/No** | **Duration** | **Number of Rounds** |
| PPT |  |  |  |
| Aptitude Test |  |  |  |
| Technical Test |  |  |  |
| Group Discussion |  |  |  |
| Technical Interview |  |  |  |
| HR Interview |  |  |  |
| Other |  |  |  |

**Interview Details**

|  |  |
| --- | --- |
| Number of Panelist |  |
| Number of Rooms  Required |  |

**Contact Details**

|  |  |
| --- | --- |
| Contact Person |  |
| Designation |  |
| Office Address |  |
| Mobile Number |  |
| Email-id |  |